

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Re application of: Mayer et al.

Atty Dkt No: NOVLP081D1/NVLS-000261

Application No.: 09/716,016

Examiner: Leader, William

Filed: November 16, 2000

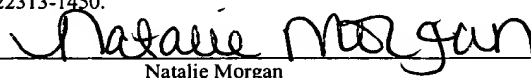
Group: 1741

Title: PROCESS FOR ELECTROPLATING  
METALS INTO MICROSCOPIC RECESSED  
FEATURES

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on July 2, 2004 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: \_\_\_\_\_

  
Natalie Morgan

**SEPARATE LETTER TO THE OFFICIAL DRAFTSMAN  
REQUESTING ENTERING OF FORMAL DRAWINGS  
(MPEP 608.02(p))**

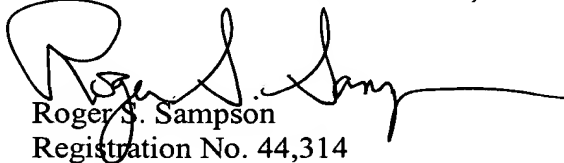
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the objections made due to informalities in the original drawings (or to corrections approved by the Examiner), enclosed are substitute (formal) drawings for the above-identified patent application. If the Draftsman has any question concerning these drawings, he or she is respectfully requested to contact the undersigned.

Respectfully submitted,

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